

Set Name side by side	Query	Hit Count	Set Name result set			
DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ						
<u>L26</u>	L25 and print job	69	<u>L26</u>			
<u>L25</u>	L21 and finishing	684	<u>L25</u>			
<u>L24</u>	L23 and finishing	2	<u>L24</u>			
<u>L23</u>	L22 and placeholder	111	<u>L23</u>			
<u>L22</u>	slipsheet or banner or control sheet	21230	<u>L22</u>			
<u>L21</u>	slipsheet or banner or control sheet or placeholder	22670	<u>L21</u>			
<u>L20</u>	115 and print job	133	<u>L20</u>			
<u>L19</u>	L17 and l15	5	<u>L19</u>			
<u>L18</u>	literal with finishing	0	<u>L18</u>			
<u>L17</u>	abstract with finishing	79	<u>L17</u>			
<u>L16</u>	L15 and pre\$flight	3	<u>L16</u>			
<u>L15</u>	select\$3 with finishing	3681	<u>L15</u>			
<u>L14</u>	preflight same stapl\$4	0	<u>L14</u>			
<u>L13</u>	L8 and job ticket	9	<u>L13</u>			
<u>L12</u>	L10 and finishing	45	<u>L12</u>			
<u>L11</u>	L10 and 14	5	<u>L11</u>			
<u>L10</u>	collat\$4 and registration and bind\$3 and cut\$4 and hole	101	<u>L10</u>			
<u>L9</u>	L6 and 13	354	<u>L9</u>			
<u>L8</u>	L6 and 14	756	<u>L8</u>			
<u>L7</u>	L6 and 15	245	<u>L7</u>			
<u>L6</u>	(alternat\$4 or substitu\$5)	2268945	<u>L6</u>			
<u>L5</u>	finishing and user (profile or preference)	312	<u>L5</u>			
<u>L4</u>	finishing same (profile or preference)	2370	<u>L4</u>			
<u>L3</u>	finishing with (profile or preference)	1329	<u>L3</u>			
<u>L2</u>	pre\$flight\$3 same finishing	1	<u>L2</u>			
<u>L1</u>	pre\$flight\$3 with finishing	1	<u>L1</u>			

END OF SEARCH HISTORY

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O-Basic O-Advanced	1 Reliability of lead free solder joint by using chip size package			
Joint FEE Joint FEE Establish IEEE Web Account Access the IEEE Member Digital Library	Hirano, T.; Fukuda, K.; Ito, K.; Kiga, T.; Taniguchi, Y.; Electronics and the Environment, 2001. Proceedings of the 2001 IEEE International Symposium on , 2001 Page(s): 285 -289			
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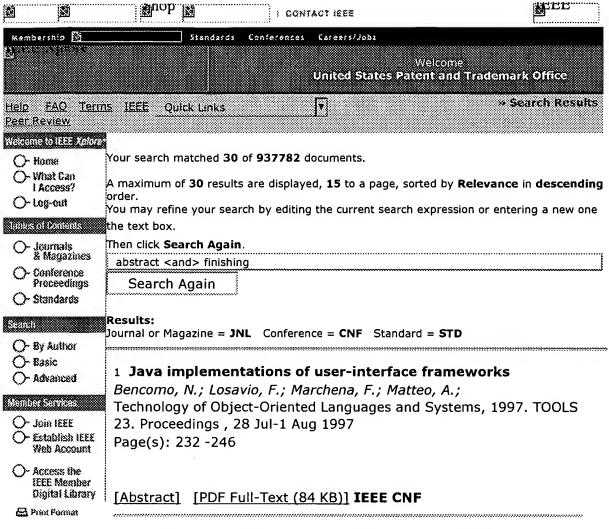
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